



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR DPAK, TO-252</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HR./CYC</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
BOND INT	160	80 000	200 °C + N2	0	0
HAST	903	90 300	130 °C, 85 % RH	0	0
Power Cycle	488	7 320 000	DELTA T <sub>j</sub> = 100 °C	0	0
Pressure Pot	958	91 968	121°, 15 PSIG	0	0
Solder DUNK	105	315	260 °C, 10 s	0	0
Solderability	60	270	883 M2003	0	0
Temp. Cycle	1140	1 050 000	-55 °C to 150 °C	0	0